Unit: mm

TOSHIBA Field Effect Transistor Silicon N Channel MOS Type (π–MOSV)

2SK2916

DC-DC Converter, Relay Drive and Motor Drive Applications

• Low drain–source ON resistance : RDS (ON) = 0.35 Ω (typ.)

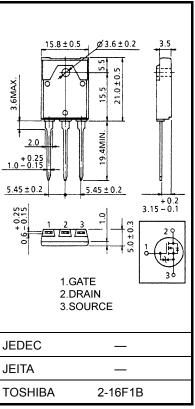
• High forward transfer admittance $: |Y_{fs}| = 11 \text{ S (typ.)}$

• Low leakage current $: I_{DSS} = 100 \mu A \text{ (max) (V}_{DS} = 500 \text{ V)}$

• Enhancement mode : $V_{th} = 2.0 \sim 4.0 \text{ V (V}_{DS} = 10 \text{ V, I}_{D} = 1 \text{ mA})$

Absolute Maximum Ratings (Ta = 25°C)

Characteris	stics	Symbol	Rating	Unit
Drain-source voltage		V_{DSS}	500	V
Drain-gate voltage (Ro	_{SS} = 20 kΩ)	V_{DGR}	500	V
Gate-source voltage		V_{GSS}	±30	V
Drain current	DC (Note 1)	ΙD	14	Α
	Pulse (Note 1)	I _{DP}	56	Α
Drain power dissipation	n (Tc = 25°C)	P_{D}	80	W
Single pulse avalanche	e energy (Note 2)	E _{AS}	795	mJ
Avalanche current		I _{AR}	14	Α
Repetitive avalanche energy (Note 3)		E _{AR}	8	mJ
Channel temperature		T _{ch}	150	°C
Storage temperature ra	ange	T _{stg}	-55~150	°C



Weight: 5.8 g (typ.)

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings. Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/Derating Concept and Methods) and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Thermal Characteristics

Characteristics	Symbol	Max	Unit
Thermal resistance, channel to case	R _{th (ch-c)}	1.56	°C/W
Thermal resistance, channel to ambient	R _{th (ch-a)}	41.6	°C/W

Note 1: Ensure that the channel temperature does not exceed 150°C.

Note 2: V_{DD} = 90 V, starting T_{ch} = 25°C, L = 6.9 mH, R_{G} = 25 Ω , I_{AR} = 14 A

Note 3: Repetitive rating: pulse width limited by maximum channel temperature

This transistor is an electrostatic-sensitive device.

Please handle with caution.



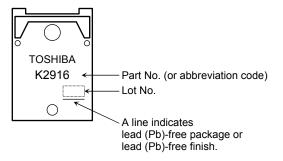
Electrical Characteristics (Ta = 25°C)

Charac	eteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage cu	rrent	I _{GSS}	V _{GS} = ±25 V, V _{DS} = 0 V	_	_	±10	μΑ
Gate-source bre	eakdown voltage	V (BR) GSS	I _G = ±10 μA, V _{DS} = 0 V	±30	_	_	V
Drain cut-off cur	rrent	I _{DSS}	V _{DS} = 500 V, V _{GS} = 0 V		_	100	μΑ
Drain-source br	eakdown voltage	V (BR) DSS	I _D = 10 mA, V _{GS} = 0 V	500	_	_	V
Gate threshold v	oltage	V _{th}	V _{DS} = 10 V, I _D = 1 mA	2.0	_	4.0	V
Drain-source Ol	N resistance	R _{DS} (ON)	V _{GS} = 10 V, I _D = 7.0 A		0.35	0.4	Ω
Forward transfer	admittance	Y _{fs}	V _{DS} = 10 V, I _D = 7.0 A	6	11	_	S
Input capacitano	е	C _{iss}			2600	_	pF
Reverse transfer capacitance		C _{rss}	V _{DS} = 10 V, V _{GS} = 0 V, f = 1 MHz	-	280	_	
Output capacitance		Coss			880	_	
Switching time	Rise time	t _r	V _{GS} _{0V} I _D =7.0A _O V _{OUT} _{R_L=30Ω}	_	50	_	ns
	Turn-on time	t _{on}		_	85	_	
	Fall time	t _f		_	65	_	
	Turn-off time	t _{off}	$V_{DD} = 210V$ Duty \le 1\%, t _w = 10\mus	_	260	_	
Total gate charge (gate-source plus gate-drain)		Qg	V _{DD} ≈ 400 V, V _{GS} = 10 V, I _D = 14 A		58	_	nC
Gate-source charge		Q _{gs}			36		
Gate-drain ("miller") Charge		Q_{gd}			22	_	

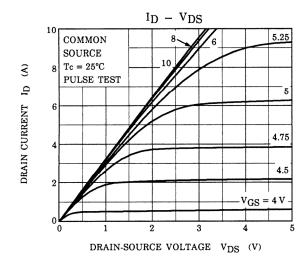
Source-Drain Ratings and Characteristics (Ta = 25°C)

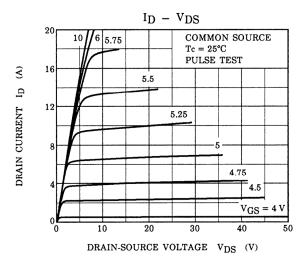
Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Continuous drain reverse current (Note 1)	I _{DR}	_	_	_	14	Α
Pulse drain reverse current (Note 1)	I _{DRP}	_	_	_	56	Α
Forward voltage (diode)	V_{DSF}	I _{DR} = 14 A, V _{GS} = 0 V	_	_	-1.7	V
Reverse recovery time	t _{rr}	I _{DR} = 14 A, V _{GS} = 0 V		400	_	ns
Reverse recovery charge	Qrr	dl _{DR} / dt = 100 A / μs	_	4.3	_	μC

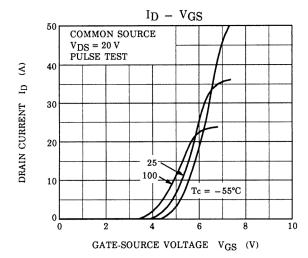
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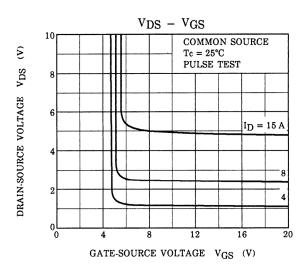


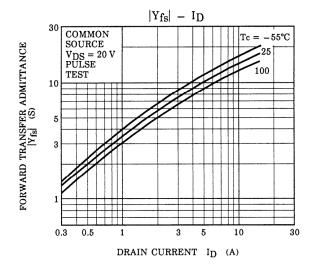
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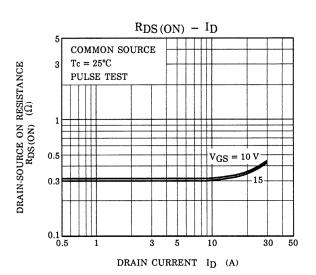


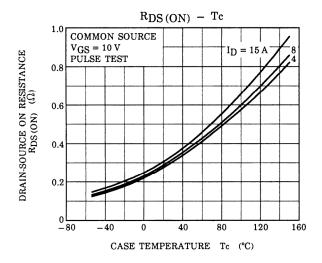


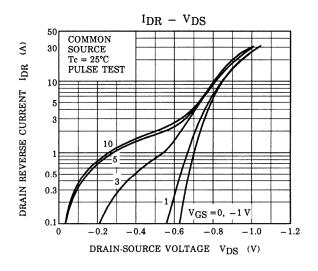


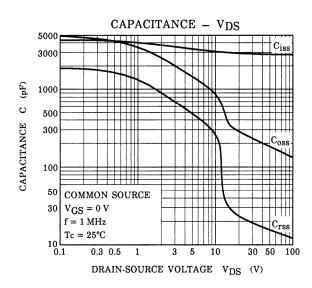


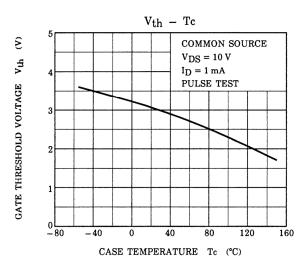


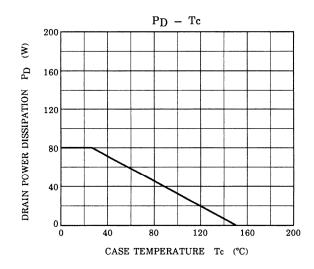


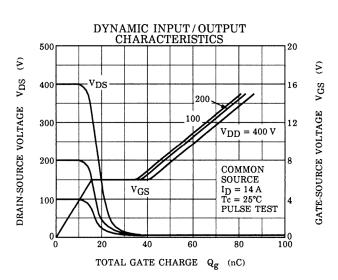


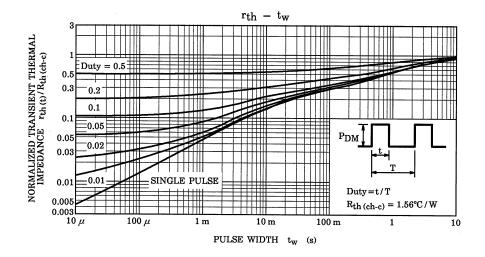


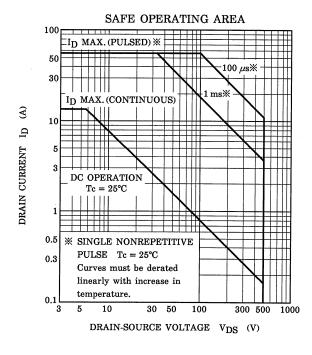


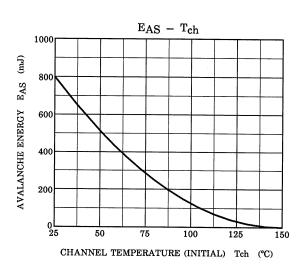


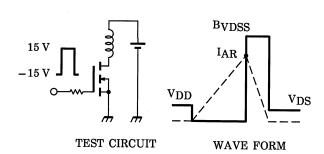












$$R_G$$
 = 25 Ω V_{DD} = 90 V, L = 6.9 mH

$$E_{AS} = \frac{1}{2} \cdot L \cdot I^{2} \cdot \left(\frac{B_{VDSS}}{B_{VDSS} - V_{DD}} \right)$$

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